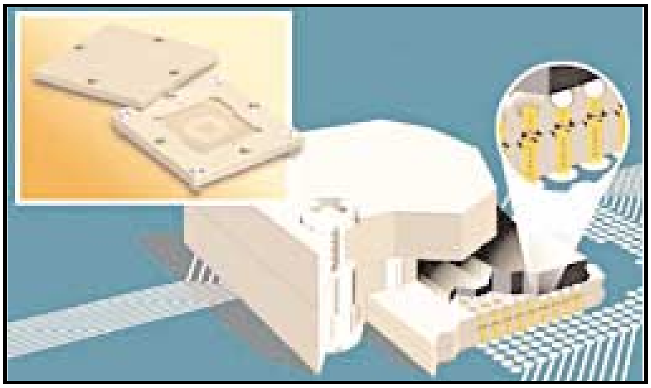
CSP/Ballnest™ Hybrid Socket

FEATURES:
- Any grid size available on 0.50mm pitch or larger.
- Socket lid nests device into female socket for a reliable, solderless electrical connection.
- Suitable for prototyping, test or burn-in of CSP, BGA, μBGA and LGA devices.
- ZIF style socket using Aries “Touchspring” contacts.
- Special lid designs and/or materials can be quoted.
- Solderless, gold plated pressure mount contact.
- Socket easily located, mounted & removed from PCB.

SPECIFICATIONS:
- Body material is Peek.
- Contacts are Beryllium Copper Alloy.
- Contact plating is 30μ”[.75μm] min. Gold per MIL-G-45204 over 30μ [.75μm] Nickel per QQ-N-290.
- Screws and alignment pins are stainless steel.
- Inserts are Brass Alloy per QQ-B-626, Tin/Lead Plated.
- Durability=10,000 cycles max.
- Spring Contact Force = 15 grams/contact avg.
- Operating Temperature Range = -55ºC to 150ºC(-67ºF to 302ºF).

All tolerances ± .005[.13] unless otherwise specified



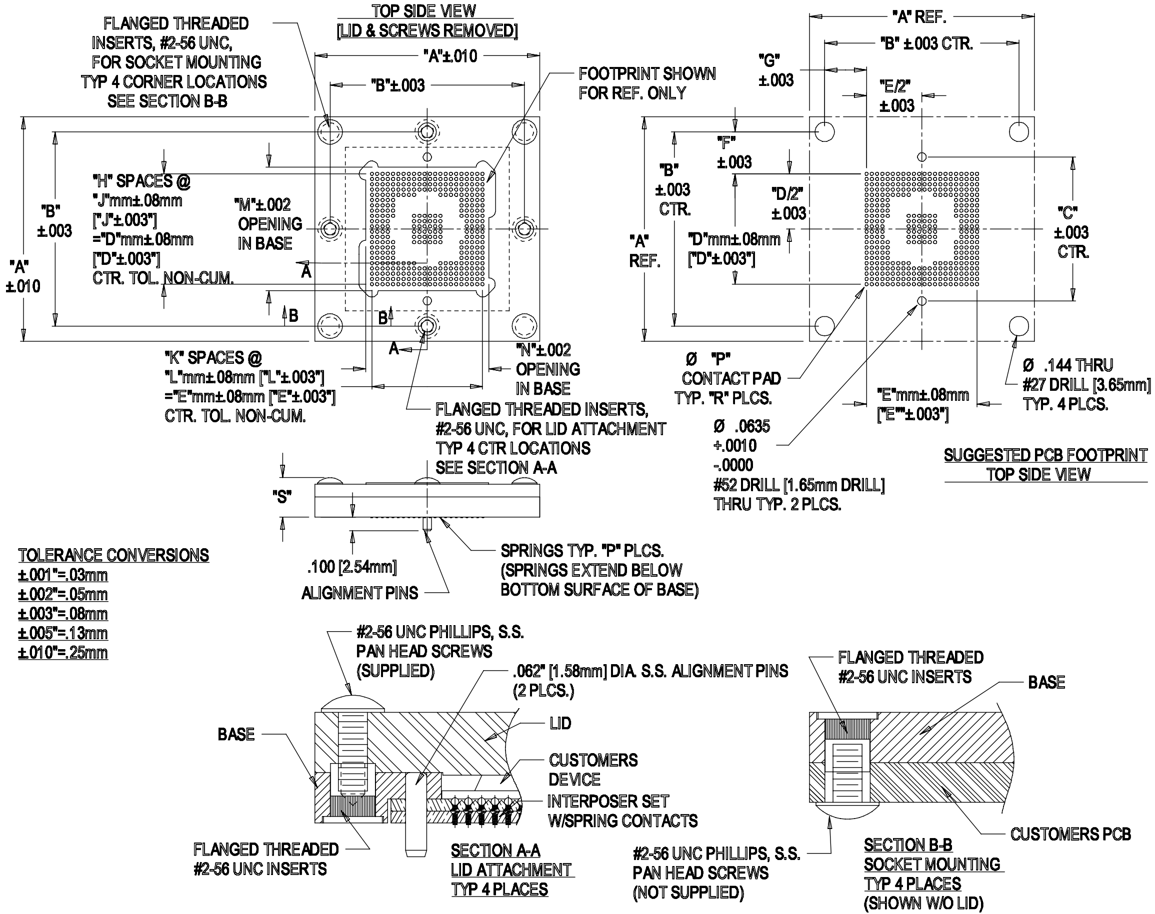
Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

ORDERING INFORMATION

Consult Factory for part number

Detailed device drawing must be sent to Aries to quote and design a socket	Use Aries’ BGA Order Sheet, Data Sheet No. 23000 for prompt quotations

ALL DIMENSIONS: INCHES [MILLIMETERS] Consult Aries for dimensions “A” - “S”



TOLERANCE CONVERSIONS
±.001"=.03mm
±.002"=.05mm
±.003"=.08mm
±.005"=.13mm
±.010"=.25mm

ARIES® ELECTRONICS, INC.
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